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Docket No.: 09450/100K673-US2
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Masahiko Furuno et al.

Application No.: Not Yet Assigned

Art Unit: N/A

Filed: Concurrently Herewith

Examiner: Not Yet Assigned

For: BUMP FORMING METHOD,
PRESOLDERING TREATMENT METHOD,
SOLDERING METHOD, BUMP FORMING
APPARATUS, PRESOLDERING
TREATMENT DEVICE AND SOLDERING
APPARATUS-

FIRST PRELIMINARY AMENDMENT

MS Patent Application
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

INTRODUCTORY COMMENTS

Prior to examination on the merits, please amend the above-identified U.S. patent application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 8 of this paper.